

CONDUCTOR SUBSTRATE, SEMICONDUCTOR DEVICE  
AND PRODUCTION METHOD THEREOF

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ABSTRACT OF THE DISCLOSURE

10       A conductor substrate for mounting a semiconductor  
element, at least a portion thereof mounting the  
semiconductor element being sealed with an insulating  
resin, wherein an uppermost surface layer of the  
conductor substrate comprises copper or an alloy thereof,  
and the conductor substrate is partly or entirely covered  
15       with a layer of copper oxide containing a hydroxide  
formed upon the surface treatment of the conductor  
substrate and a process of producing the conductor  
substrate as well as a process for the production of a  
semiconductor device using the conductor substrate.